



# 100% Material Declaration Data Sheet VO8

PK174 (v1.1) February 20, 2007

Material Declaration Data Sheet

**Average Weight: 0.524 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.0127</b>	<b>2.43%</b>
	Silicon	7440-21-3	99.00		0.0126	
	Al	7429-90-5	1.00		0.0001	
<b>Die Attach Material</b>					<b>0.0028</b>	<b>0.54%</b>
	Epoxy resin(EP)	29690-82-2	25.00		0.0007	
	Silver	7440-22-4	75.00		0.0021	
<b>Encapsulation</b>					<b>0.3443</b>	<b>65.76%</b>
	Resin	29690-82-2	26.00		0.0913	
	SiO2 Filler	60676-86-0	74.00		0.253	
<b>Leadframe</b>					<b>0.1552</b>	<b>29.65%</b>
	Iron	7439-89-6	58.00		0.090	
	Nickel	7440-02-0	42.00		0.0652	
<b>Bond Wire</b>					<b>0.0007</b>	<b>0.13%</b>
	Gold	7440-57-5	100.00		0.0007	
<b>Ext. Plating</b>					<b>0.0078</b>	<b>1.49%</b>
	Tin	7440-31-5	85.00		0.0066	
	Lead	7439-92-1	15.00		0.0012	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
9/25/06	1.0	Initial release.
2/20/07	1.1	Updated component descriptions and weights.